

**AMENDMENTS TO THE SPECIFICATION**

Please replace the paragraph at page 1, line 7 with the following rewritten paragraph:

-- The present invention relates to a novel dicing and die bonding pressure-sensitive adhesive sheet. More particularly, the invention relates to a dicing and die bonding pressure-sensitive adhesive sheet that is particularly suitable for use in the process of dicing and silicon wafer or the like into chips and bonding the resultant ~~die~~ chips onto die pads of a substrate such as a lead frame. --

Please delete the section heading at page 3, line 19.

Please replace the section heading at page 4, line 6 with the following rewritten section heading:

-- ~~DISCLOSURE~~SUMMARY OF THE INVENTION --

Please delete the section heading at page 5, line 16.

Please replace the section heading at page 6, line 3 with the following rewritten section heading:

-- ~~PREFERRED EMBODIMENTS~~DETAILED DESCRIPTION OF THE INVENTION--

Please replace the section heading at page 8, line 3 with the following rewritten section heading:

-- {Pressure-sensitive component (A)}--

Please replace the section heading at page 10, line 6 with the following rewritten section heading:

-- {Thermosetting component (B)}--

Please replace the section heading at page 13, line 18 with the following rewritten section heading:

-- {Thermoplastic resin (C)}--

Please replace the section heading at page 14, line 23 with the following rewritten section heading:

-- {Energy ray curing component (D)}--

Please replace the section heading at page 17, line 3 with the following rewritten section heading:

-- {Further additive (E)}--

Please replace the section heading at page 19, line 17 with the following rewritten section heading:

-- {Pressure-sensitive adhesive layer}--

Please replace the section heading at page 20, line 9 with the following rewritten section heading:

-- {Dicing and die bonding pressure-sensitive adhesive sheet}--

Please replace the section heading at page 23, line 9 with the following rewritten section heading:

-- {Method of using the dicing and die bonding pressure-sensitive adhesive sheet}--

Please replace the section heading at page 26, line 18 with the following rewritten section heading:

-- {Modulus of elasticity}--

Please replace the section heading at page 27, line 3 with the following rewritten section heading:

-- {Dicing properties}--

Please replace the section heading at page 27, line 9 with the following rewritten section heading:

-- {Embedding properties at die bonding}--

Please replace the section heading at page 27, line 17 with the following rewritten section heading:

-- {Bond strength}--

Please replace the section heading at page 28, line 6 with the following rewritten section heading:

-- {Package reliability}--

Please replace the section heading at page 28, line 16 with the following rewritten section heading:

-- {Board mounting reliability}--

Please replace the section heading at page 29, line 7 with the following rewritten section heading:

-- {Pressure-sensitive adhesive layer}--

Please replace the section heading at page 31, line 9 with the following rewritten section heading:

-- {Examples and Comparative Examples}--

Please delete the heading at page 36, line 1.

Please replace the paragraph at page 36, line 2 with the following rewritten paragraph:

-- ~~The~~From the foregoing description, it will be understood that the dicing and die bonding pressure-sensitive adhesive sheet of the invention has ~~the~~ a pressure-sensitive adhesive layer that exhibits superior embedding properties with respect to irregularities on the die pads under die bonding conditions. Therefore, the sheet can prevent formation of voids between the die pads and the pressure-sensitive adhesive layer even when chips are mounted on die pads ~~having exhibiting great difference of~~ differences in height, to thereby ~~contributes~~ contribute to improve production efficiency. --